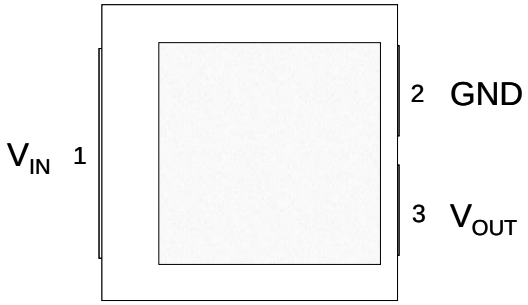
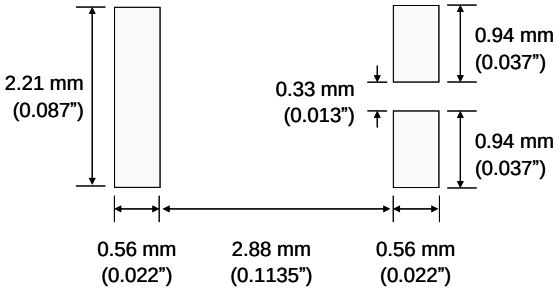
CONFIGURATION INFORMATION

Pin Configuration (Top View)



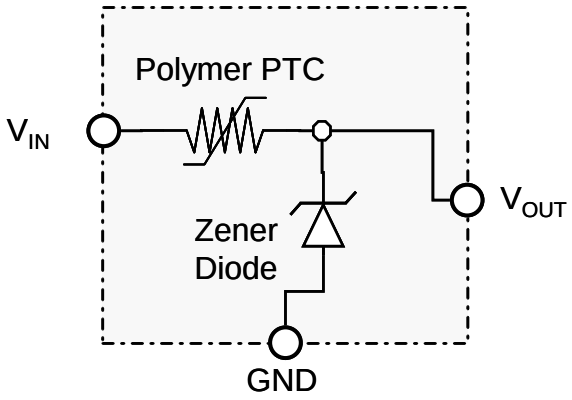
Pad Dimensions



PIN DESCRIPTION

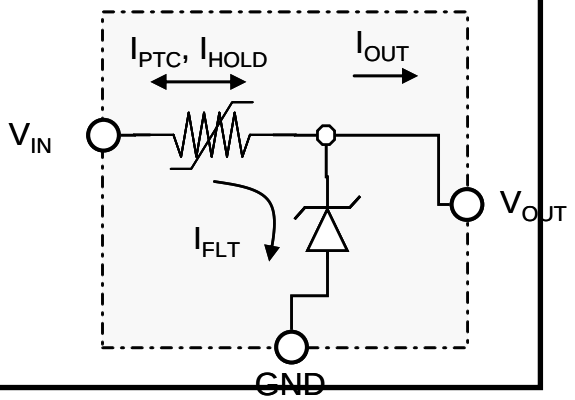
Pin Number	Pin Name	Pin Function
1	V_{IN}	**V_{IN}.** Protected input to Zener diode.
2	GND	**GND**
3	V_{OUT}	**V_{OUT}.** Zener regulated voltage output

BLOCK DIAGRAM



DEFINITION of TERMS

I_{PTC}	Current flowing through the PTC portion of the circuit
I_{FLT}	RMS fault current flowing through the diode
I_{OUT}	Current flowing out the V_{OUT} pin of the device
Trip Event	A condition where the PTC transitions to a high resistance state, thereby significantly limiting I_{PTC} and related currents.
Trip Endurance	Time the PTC portion of the device remains in a high resistance state.



GENERAL SPECIFICATIONS

Operating Temperature	-40º to +85ºC
Storage Temperature	-40º to +85ºC

ELECTRICAL CHARACTERISTICS[1-3, 11] (Typical unless otherwise specified)

V_Z[4] (V)			I_{zt}[4] (A)	I_{HOLD}[5] @20º C (A)	Leakage Current		R Typ[6] (Ohms)	R_{1Max}[7] (Ohms)	V_{Int} Max[8] (V)		I_{FLT} Max[9]		Tripped Power Dissipation[10] Max	
Min	Typ	Max			Test Voltage	Max Current (mA)			V_{INT} Max (V)	Test Current (A)	I_{FLT} Max (A)	Test Voltage (V)	Value (W)	Test Voltage (V)
9.6	9.8	10.0	0.1	1.3	9.5	5	0.12	0.16	24V	3A	+3.5 -40	+24 -16V	1.0	24

Note 1: Electrical characteristics determined at 25ºC unless otherwise specified.

Note 2:This device is intended for limited fault protection. Repeated trip events or extended trip endurance can degrade the device and may affect performance to specifications. Performance impact will depend on multiple factors including, but not limited to, voltage, trip current, trip duration, trip cycles, and circuit design. For details or ratings specific to your application contact, Littelfuse Circuit Protection Division directly.

Note 3:Specifications developed using 1.0 ounce 0.045" wide copper traces on dedicated FR4 test boards. Performance in your application may vary.

Note 4:I_{zt} is the current at which V_z is measured ($V_Z = V_{OUT}$). Additional V_Z values are available on request.

Note 5:I_{HOLD} : Maximum steady state I_{PTC} (current entering or exiting the V_{IN} pin of the device) that will not generate a trip event at the specified temperature. Specification assumes I_{FLT} (current flowing through the Zener diode) is sufficiently low so as to prevent the diode from acting as a heat source. Testing is conducted with an "open" Zener.

Note 6:R Typ: Resistance between V_{IN} and V_{OUT} pins during normal operation at room temperature.

Note 7:R_{1Max}:The maximum resistance between V_{IN} and V_{OUT} pins at room temperature, one hour after 1st trip or after reflow soldering.

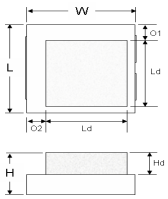
Note 8:V_{INT} Max: V_{INT} Max relates to the voltage across the PPTC portion of the PolyZen device (V_{IN}-V_{OUT}). V_{INT} Max is defined as the voltage (V_{IN}-V_{OUT}) at which typical qualification devices (98% devices, 95% confidence) survived at least 100 trip cycles and 24 hours trip endurance at the specified voltage (V_{IN}-V_{OUT}) and current (I_{PTC}). V_{INT} Max testing is conducted using a "shorted" load (V_{OUT} = 0 V). V_{INT} Max is a survivability rating, not a performance rating.

Note 9:I_{FLT} Max: I_{FLT} Max relates to the steady state current flowing through the diode portion of the PolyZen device in a fault condition, prior to a trip event. I_{FLT} Max is defined as the current at which typical qualification devices (12 parts per lot from 3 lots) survived 100 test cycles. RMS fault current above I_{FLT} Max may permanently damage the diode portion of the PolyZen device. Testing is conducted with NO load connected to V_{OUT}, such that I_{OUT} = 0. "Test voltage" is defined as the voltage between V_{IN} to GND and includes the PolyZen Diode drop. Specification is dependent on the direction of current flow through the diode. I_{FLT} Max is a survivability rating, not a performance rating.

Note 10:The power dissipated by the device when in the "tripped" state, as measured on Littelfuse test boards (see note 3).

Note 11:Specifications based on limited qualification data and subject to change.

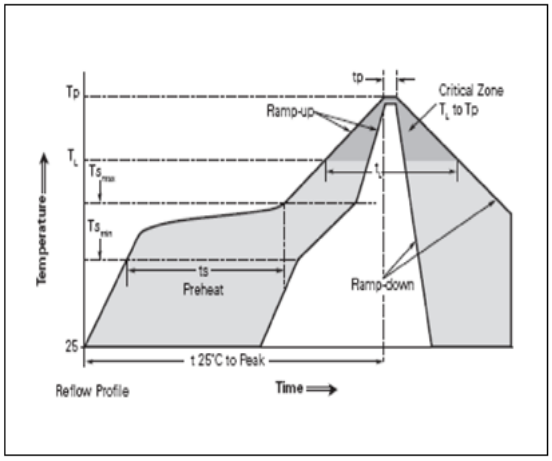
MECHANICAL DIMENSIONS



		Min	Typical	Max
Length	L	3.85 mm (0.152")	4 mm (0.16")	4.15 mm (0.163")
Width	W	3.85 mm (0.152")	4 mm (0.16")	4.15 mm (0.163")
Height	H	1.4mm (0.055")	1.7 mm (0.067")	2.0 mm (0.081")
Length Diode	Ld	-	3.0 mm (0.118")	-
Height Diode	Hd	-	1.0 mm (0.039")	-
Offset	O1	-	0.6 mm (0.024")	-
Offset	O2	-	0.7 mm (0.028")	-

SOLDER REFLOW RECOMMENDATIONS:

Classification Reflow Profiles	
Profile Feature	**Pb-Free Assembly**
Average Ramp-Up Rate (Tsmax to Tp)	3 °C/second max.
Preheat	
• Temperature Min (Tsmin)	150 °C
• Temperature Max (Tsmax)	200 °C
• Time (tsmin to tsmax)	60-180 seconds
Time maintained above:	
• Temperature (TL)	217 °C
• Time (tL)	60-150 seconds
Peak/Classification Temperature (Tp)	260 °C
Time within 5 °C of actual Peak	
Temperature (tp)	20-40 seconds
Ramp-Down Rate	6 °C/second max.
Time 25 °C to Peak Temperature	8 minutes max.

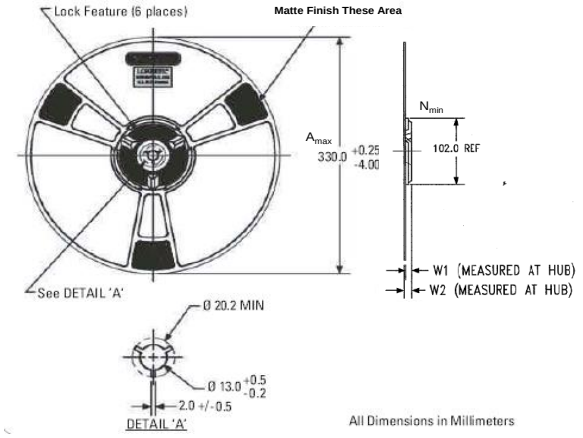


PACKAGING

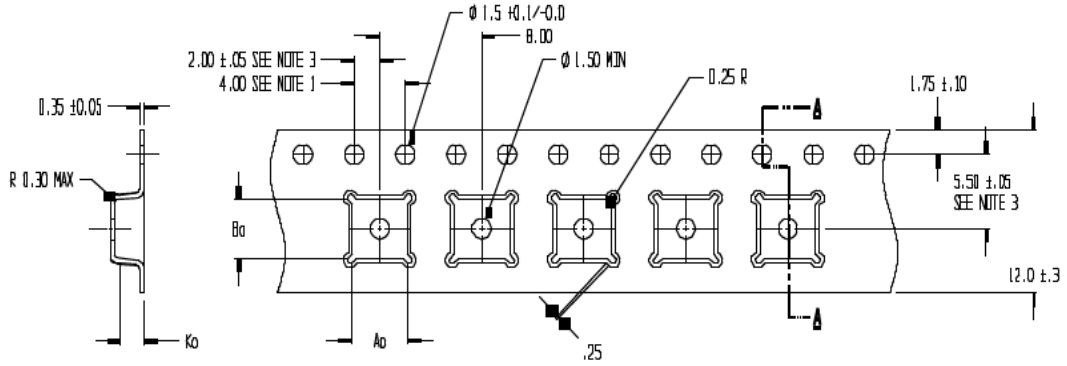
Packaging	Tape & Reel	Standard Box
ZENXXXVXXXAXXLS	3,000	15,000

Reel Dimensions for PolyZen Devices

A_{max} = 330
N_{min} = 102
W_1 = 8.4
W_2 = 11.1

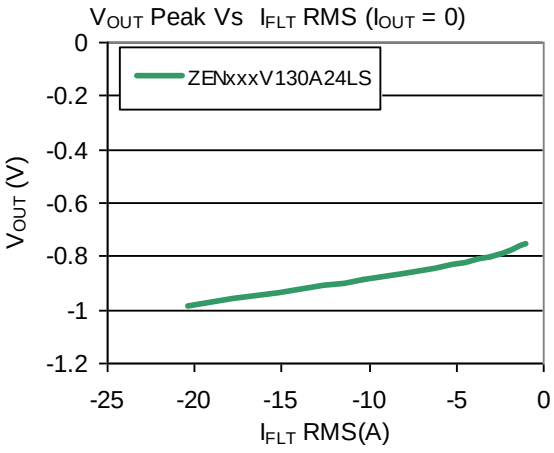


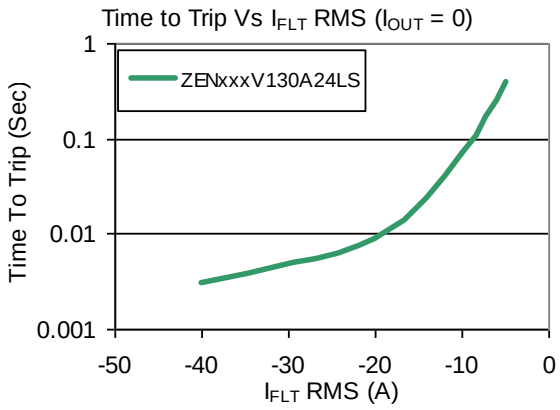
Taped Component Dimensions for PolyZen Devices

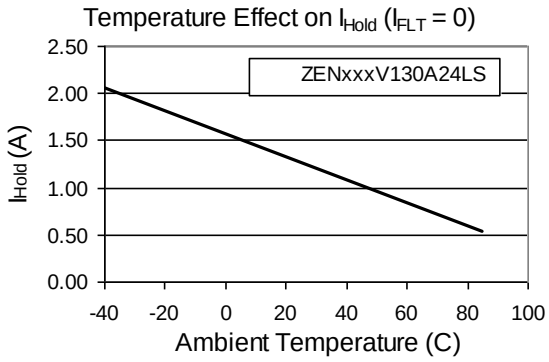


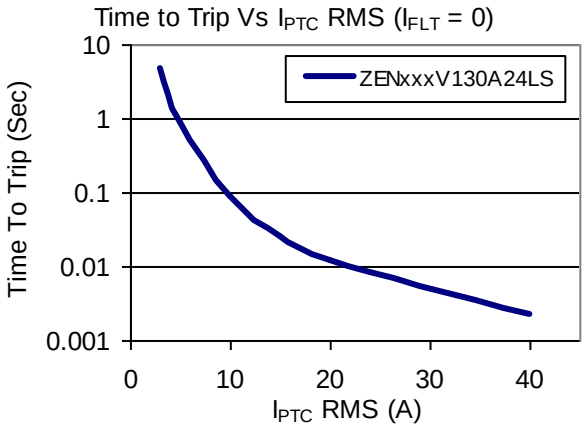
Ao = 4.35
Bo = 4.35
Ko = 2.30

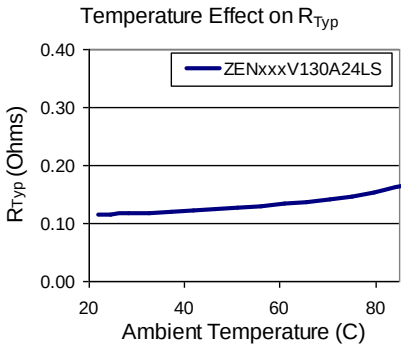
NOTES:
1. 10 SPROCKET HOLE PITCH CUMULATIVE TOLERANCE ±0.2
2. CAMBER IN COMPLIANCE WITH EIA 481
3. POCKET POSITION RELATIVE TO SPROCKET HOLE MEASURED AS TRUE POSITION OF POCKET, NOT POCKET HOLE











Materials Information

ROHS Compliant
Directive 2002/95/EC Compliant

ELV Compliant
Directive 2000/53/EC Compliant

Pb-Free